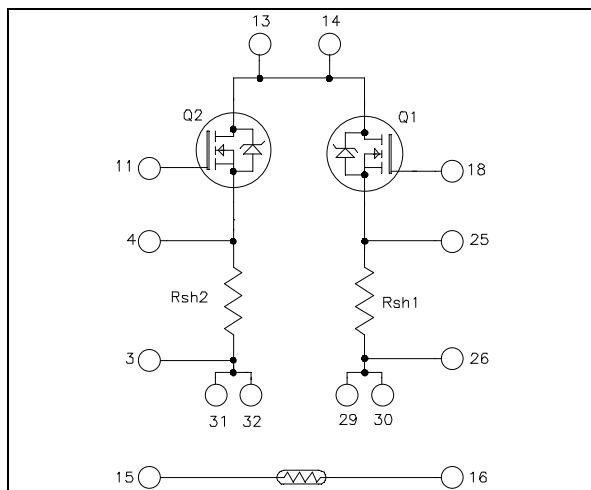


Linear MOSFET Power Module

$$V_{DSS} = 1000V$$

$$R_{DSon} = 600m\Omega \text{ typ @ } T_j = 25^\circ C$$

$$I_D = 20A \text{ @ } T_c = 25^\circ C$$



Pins 13/14 ; 29/30 ; 31/32 must be shorted together

Application

- Electronic load dedicated to power supplies and battery discharge testing

Features

- Linear MOSFET
- Very low stray inductance
- Internal thermistor for temperature monitoring
- High level of integration
- AlN substrate for improved thermal performance

Benefits

- Direct mounting to heatsink (isolated package)
- easy series and parallels combinations for power and voltage improvements
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS Compliant

Absolute maximum ratings (per leg)

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	1000	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	20
		$T_c = 80^\circ C$	14
I_{DM}	Pulsed Drain current	74	A
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	720	m Ω
P_D	Maximum Power Dissipation ❶	$T_c = 25^\circ C$	520
			W

❶ In saturation mode

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^{\circ}\text{C}$ unless otherwise specified

Electrical Characteristics (per leg)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 1000\text{V}; V_{GS} = 0\text{V}$ $T_j = 25^{\circ}\text{C}$			250	μA
		$V_{DS} = 800\text{V}; V_{GS} = 0\text{V}$ $T_j = 125^{\circ}\text{C}$			1000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10\text{V}, I_D = 10\text{A}$		600	720	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}; I_D = 2.5\text{mA}$	2		4	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30\text{V}$			± 100	nA

Dynamic Characteristics (per leg)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$		6000		pF
C_{oss}	Output Capacitance	$V_{DS} = 25\text{V}$		775		
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		285		

Shunt Electrical Characteristics (per leg)

Symbol	Characteristic	Min	Typ	Max	Unit
R_{sh}	Resistance value		20		$\text{m}\Omega$
T_{sh}	Tolerance		2		%
P_{sh}	Load capacity	$T_C = 25^{\circ}\text{C}$		20	W
		$T_C = 80^{\circ}\text{C}$		10	
I_{sh}	Current capacity	$T_C = 25^{\circ}\text{C}$		31	A
		$T_C = 80^{\circ}\text{C}$		22	

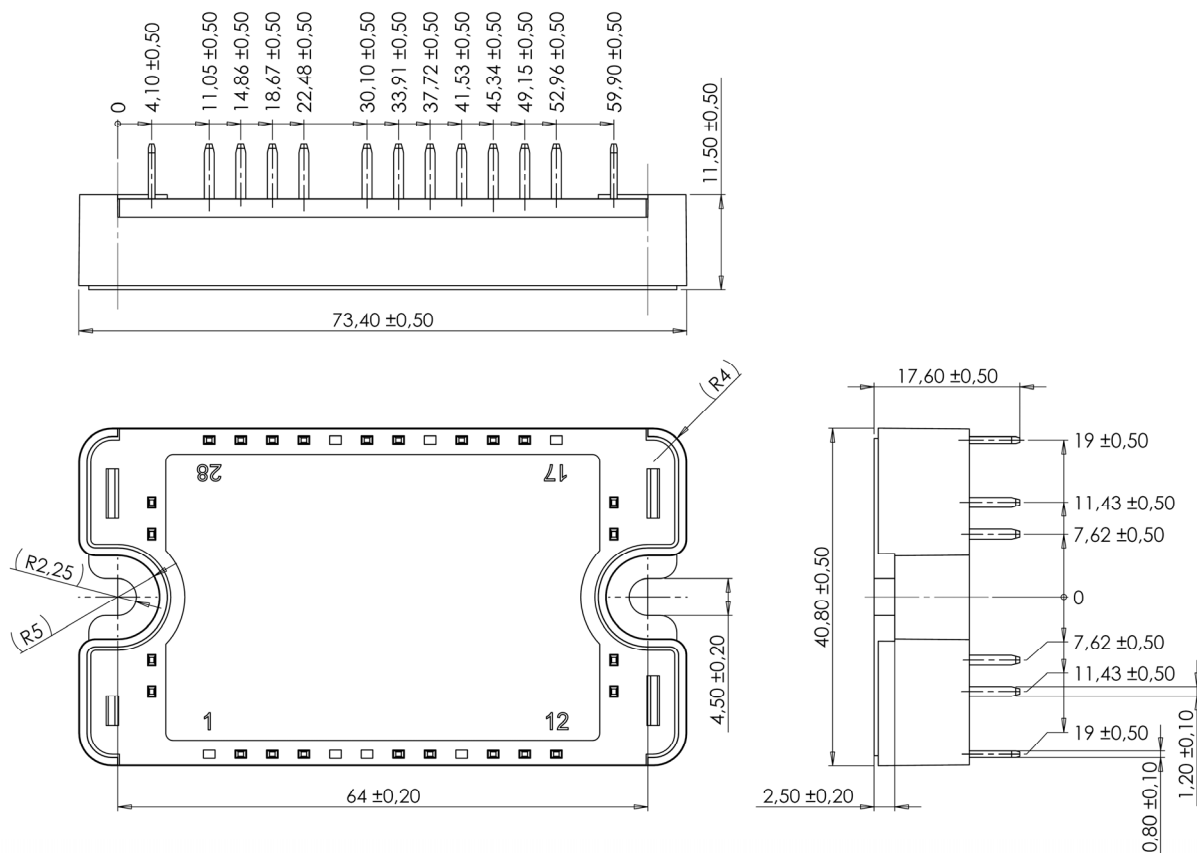
Temperature sensor PTC

Symbol	Characteristic	Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C	1980		2020	Ω
R_{100}/R_{25}	Resistance ratio	$T_{amb} = 100^{\circ}\text{C} \& 25^{\circ}\text{C}$	1.676	1.696	1.716
R_{-55}/R_{25}	Resistance ratio	$T_{amb} = -55^{\circ}\text{C} \& 25^{\circ}\text{C}$	0.48	0.49	0.50
B	Temperature coefficient		7900		ppm/K

Thermal and package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
R _{thJC}	Junction to Case Thermal Resistance		MOSFET (per leg)			0.24	°C/W
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz			4000			V
T _J	Operating junction temperature range			-40		150	°C
T _{STG}	Storage Temperature Range			-40		125	
T _C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M4	2		3	N.m
Wt	Package Weight					110	g

SP3 Package outline (dimensions in mm)



See application note 1901 - Mounting Instructions for SP3 Power Modules on www.microsemi.com

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